Timing properties of the RD50-MPW2 HVCMOS chip

Jernej Debevc 40th RD50 Workshop – June 24, 2022

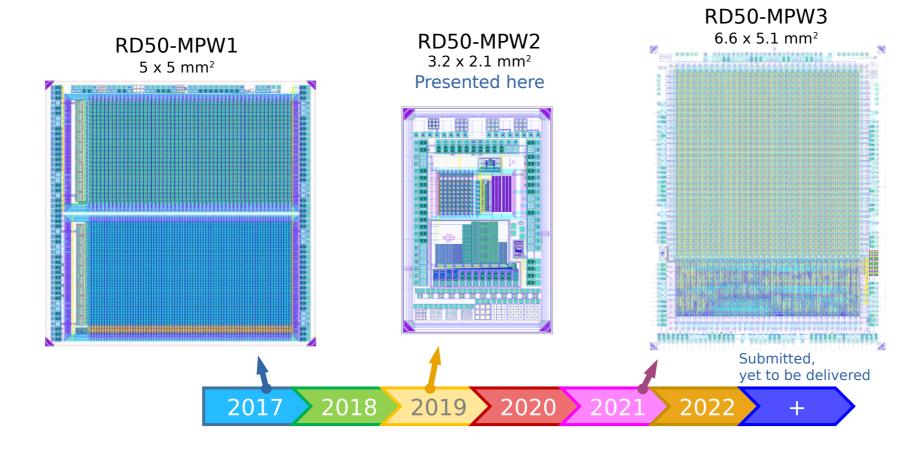
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CERN-RD50 CMOS development program

- CERN-RD50 CMOS working group
 - Program to develop and study radiation hard monolithic sensors in CMOS technology
 - 3 CMOS prototypes developed so far
 - LFoundry 150 nm HV-CMOS process
 - Large electrode design



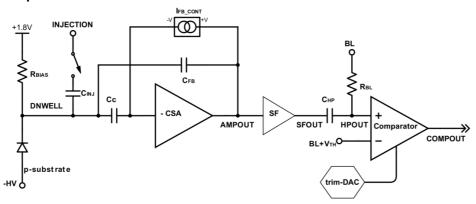
RD50-MPW2

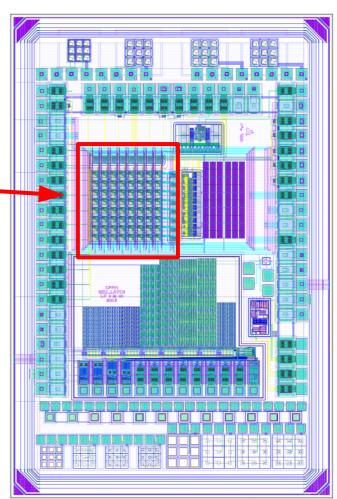
- CMOS prototype with several test structures
- p-type substrate, 4 resistivities: $20 \Omega cm 3 k\Omega cm$
- Breakdown voltage V_{bd} = 120 V

8 x 8 active pixel matrix

- 60 x 60 μm² pixel size
- Charge sensitive amplifier and discriminator
- Two pixel flavors with different CSA resets:
 - Continuous reset Time over threshold > 100 ns
 - Switched reset Time over threshold ~ 10 ns
- Analog front end

Continuous reset pixel:





2.1 mm

RD50-MPW2 DAQ

- Chip configuration and DAQ via Zync 706 SoC and Caribou system (developed by Liverpool and Vienna)
- Pixel analog and digital outputs connected to oscilloscope for measurements
- Single pixel readout only

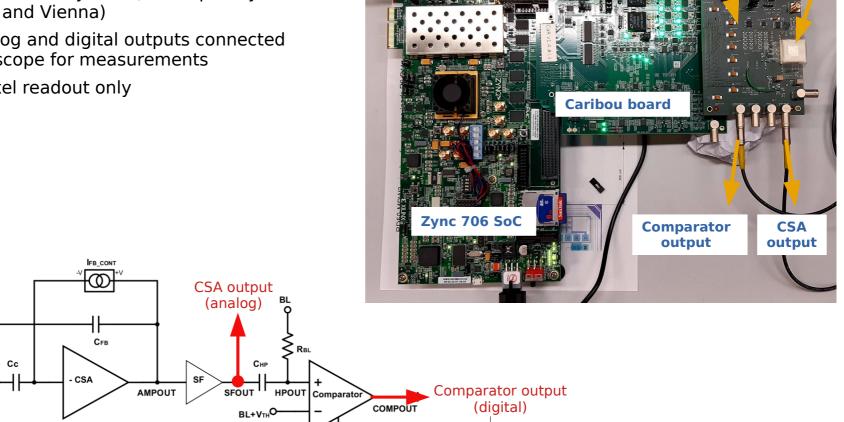
INJECTION

≤R_{BIAS}

DNWELL

p-substrate

-HA P



trim-DAC

Used for timing

measurements

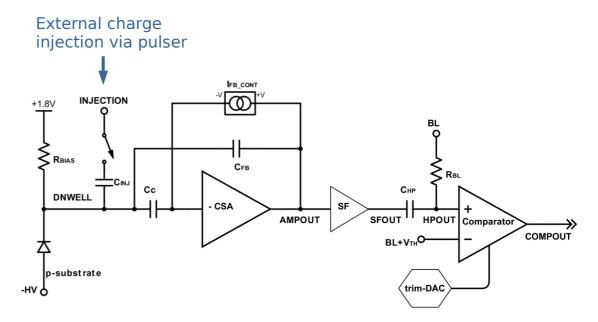
RD50-MPW2 chip board

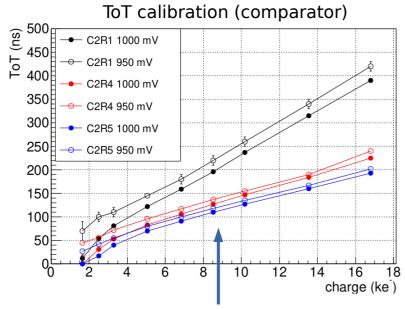
Sample

under cap

Continuous reset pixel calibration

- Calibration done via calibration circuit with injection capacitor $C_{ini} = 2.8 \text{ fF}$

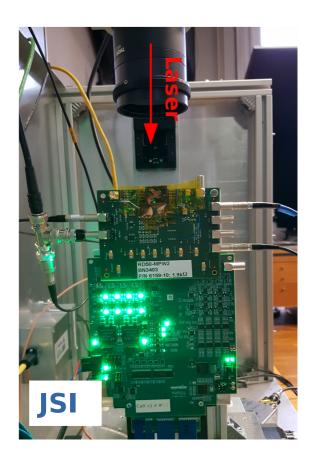


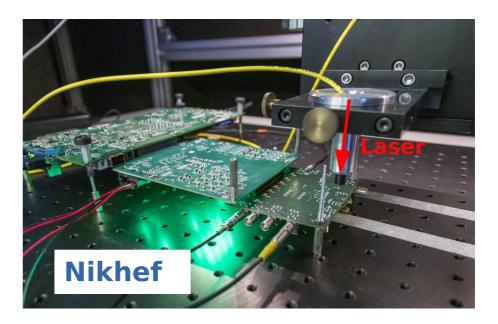


CSA output calibration

TCT setup

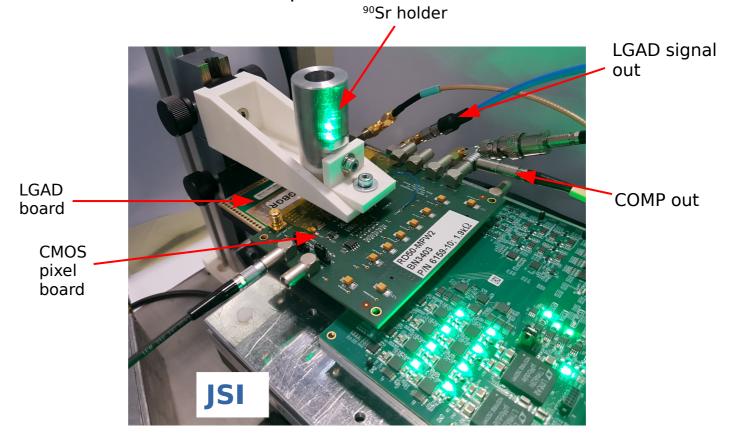
- TCT measurements with 1064 nm IR laser pulses
- Two setups:
 - Jožef Stefan Institute → Edge-TCT, Position sensitive
 - Nikhef → Back-TCT, Illumination of entire pixel





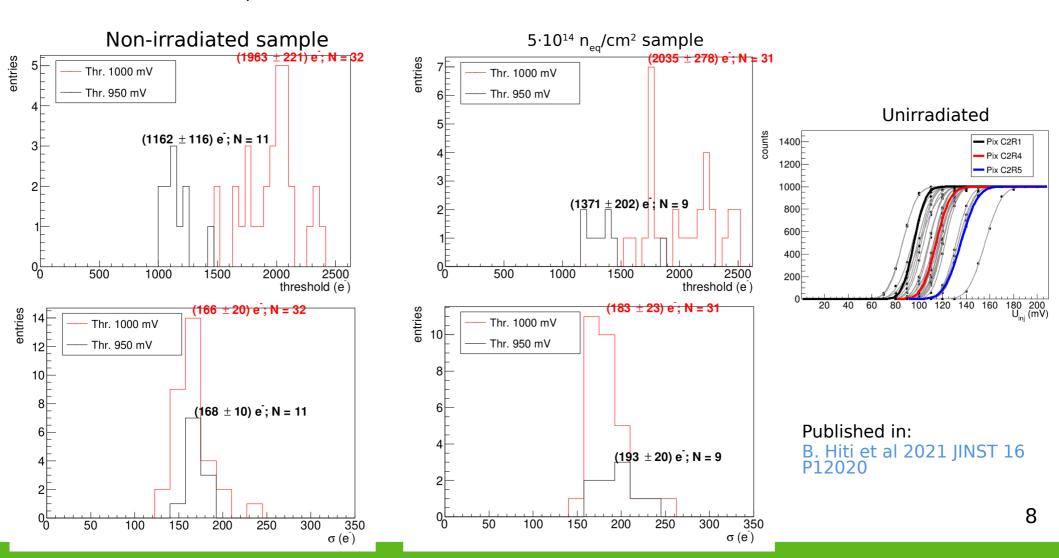
90Sr setup

- Timing measurements with 90Sr at Jožef Stefan Institute
- Reference signal from 1 x 1 mm² LGAD detector mounted on Santa Cruz timing board behind the CMOS chip
- Trigger: sample + LGAD
- LGAD jitter of ~30 ps is negligible in comparison with jitter of CMOS pixel
- Low rate: ~ 1 event/min with 18 MBq source



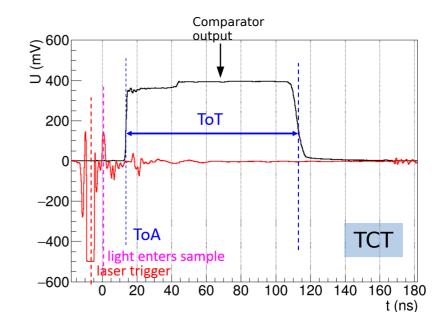
Measured samples

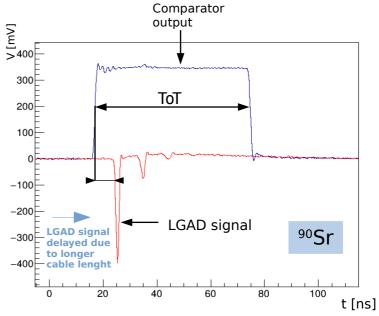
- Resistivity 1.9 kΩcm
- Unirradiated and irradiated to $5\cdot10^{14}~n_{eq}/cm^2$ (irradiation with neutrons at TRIGA reactor in Ljubljana)
- Depletion depth 180 μm (120 μm) before (after) irradiation
- Nominal comparator threshold ≈ 1 ke, 2 ke



Timing measurements - methodology

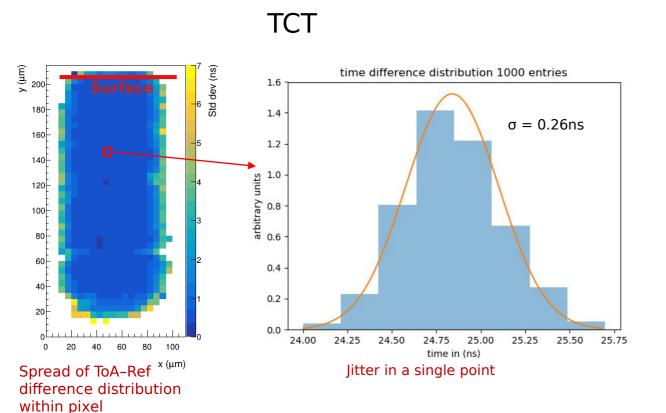
- Time walk and timing resolution (jitter) measurements with comparator output signal
 - Reference time (Trigger from laser driver, LGAD signal)
 - Time of arrival (ToA) compensated for cable length
 - Time over threshold (ToT)
- Sampling time at 50% maximum, CFD on LGAD signal, linear interpolation
 - Time walk measurements
 - Dependence of ToA on ToT
 - Average of 100 pulses

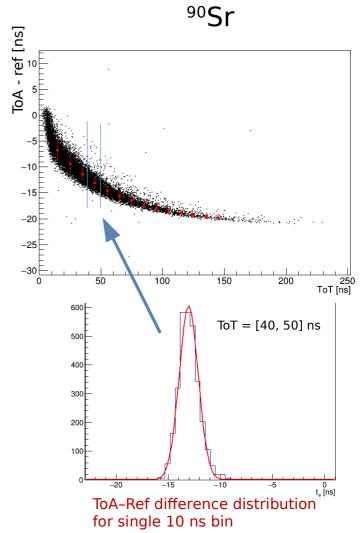




Timing measurements - methodology

- Jitter measurements
 - Spread of difference between ToA and reference signal
 - TCT: Statistics on 1000 samples
 - 90Sr: Events binned in 10 ns bins over ToT



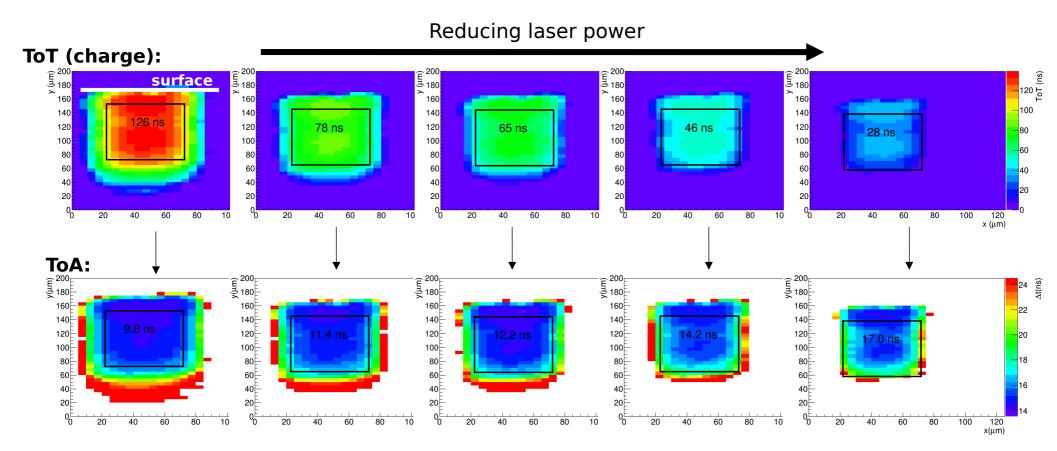


Time walk - Edge-TCT

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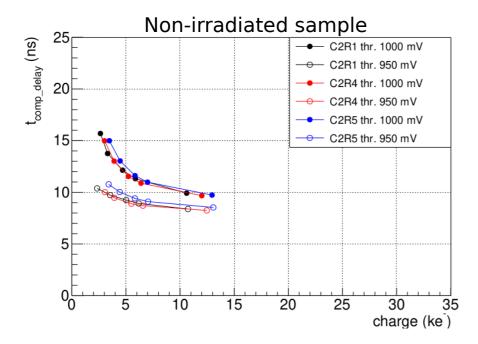
B. Hiti et al 2021 JINST 16 P12020

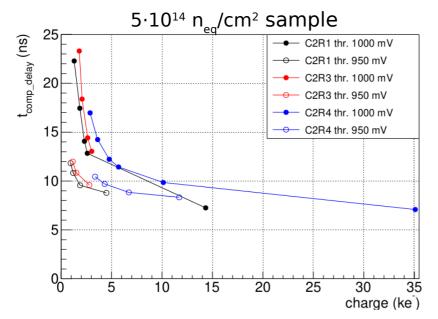
- Average of ToA and ToT over central part of pixel
- Output delay increases for smaller charge



(same z-scale for all measurements)

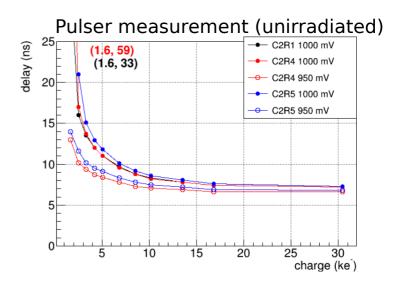
Time walk





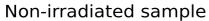
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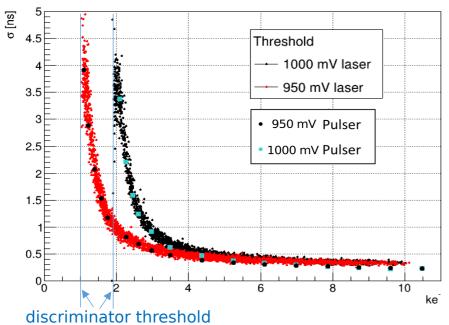
B. Hiti et al 2021 JINST 16 P12020



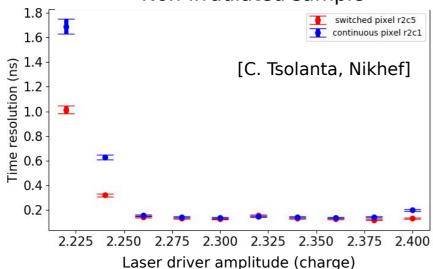
- Above 2 ke, comparator response at most 10 ns slower than the fastest signals
- Good agreement with measurements using direct charge injection (pulser) – 1 ns larger delay with TCT due to charge carrier drift

Timing resolution - TCT

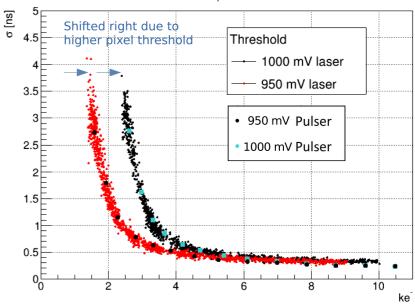




Non-irradiated sample



 $5 \cdot 10^{14} \, \text{n}_{\text{eq}} / \text{cm}^2 \, \text{sample}$



Timing resolution scales as (S/N)⁻¹ with baseline:

$$f(x) = \frac{a}{x - x_{\text{thr}}} + \sigma_{\text{asymp}}$$

 $\sigma_{
m asymp}$ fit values: 140 ps / 160 ps

Timing resolution at 10 ke: ~ 300 ps

Theoretical estimate for $\,t_{\mathrm{rise}} = 20\,\mathrm{ns}$, $\,N = 170\,\mathrm{e^-}$

$$\sigma_{\rm t} = \frac{t_{\rm rise}}{S/N} = \frac{20\,{\rm ns}}{10\,{\rm ke}^-/170\,{\rm e}^-} = 340\,{\rm ps}$$

agrees with measurements

- Good agreement of laser and pulser measurements for both samples (better asymptotic resolution for pulser)
- No significant increase in jitter after irradiation

Timing resolution - 90Sr

$5 \cdot 10^{14} \, n_{eq}/cm^2 \, sample$ Unirradiated sample Pulser Pulser 2.5 - Sr90 -- Sr90 2.5 1. 0.5 350 ToT = [30, 40] ns300 ToT = [50, 60] ns400 350 250 300 Tail towards slower 250 signal arrivals 150 200 100 150 100 50 50 -10 -20

- Timing resolution with 90Sr larger than from pulser measurements
- Unirradiated sample showing worse resolution at large charge values (\sim 600 ps) compared to irradiated sample (\sim 350 ps)
- Slow charge collection in low field regions and via diffusion in unirradiated sample → Slower signals, widening of the distribution
- Charge recombination faster in irradiated silicon + trapping of charge → Slower signals not present

Conclusions

- Timing measurements of RD50-MPW2 prototype using IR laser light in TCT and electrons from ⁹⁰Sr
- Measurements compared with direct charge injection via pulser
- Time walk within 10 ns for charges > 2 ke
- Timing resolution scales as $(S/N)^{-1}$, ≈ 150 ps asymptotic resolution
- ⁹⁰Sr measurements show larger timing resolution
 - ~ 600 ps unirradiated sample, ~ 350 ps for $5 \cdot 10^{14}~n_{eq}/cm^2$ sample
 - worse timing resolution in unirradiated sample due to significant charge collection by diffusion (slower)

Backups

90Sr measurements - Tails in distribution of unirradiated sample 5.1

 $5 \cdot 10^{14} \, n_{eq} / cm^2 \, sample$ 350 ₽ Unirradiated sample ToT = [30, 40] ns300 250 400 ToT = [50, 60] ns200 350 300 150 250 100 200 150 100 -15 -10 -5 50 100 -10 ToT = [90, 100] ns80 Tail towards slower signal arrivals 600 ToT = [130, 140] nsCharge collection by 500 diffusion 400 20 300 -10 0 t_a [ns] 200 100 Tails in distributions not present in irradiated sample

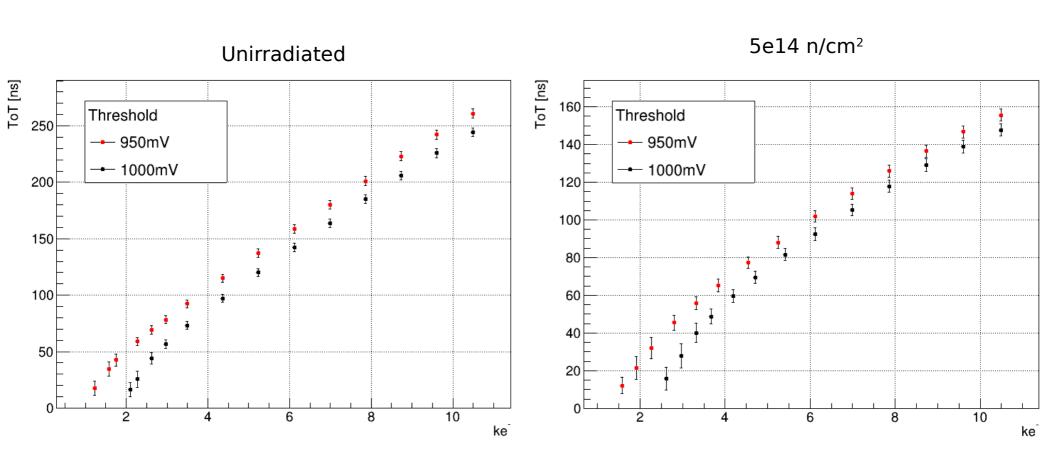
undepleted region

More charge reaching the depletion layer via diffusion in

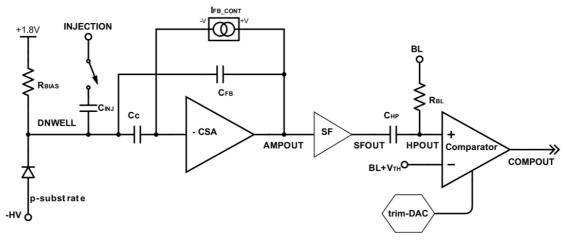
unirradiated sample due to slower recombination in

Backups

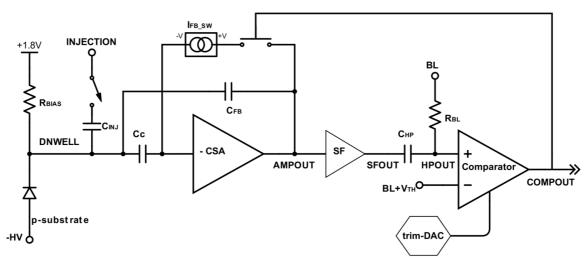
ToT calibration



Pixel circuit diagrams



Continuous reset pixel



Switched reset pixel